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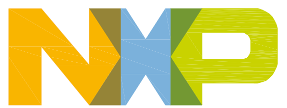
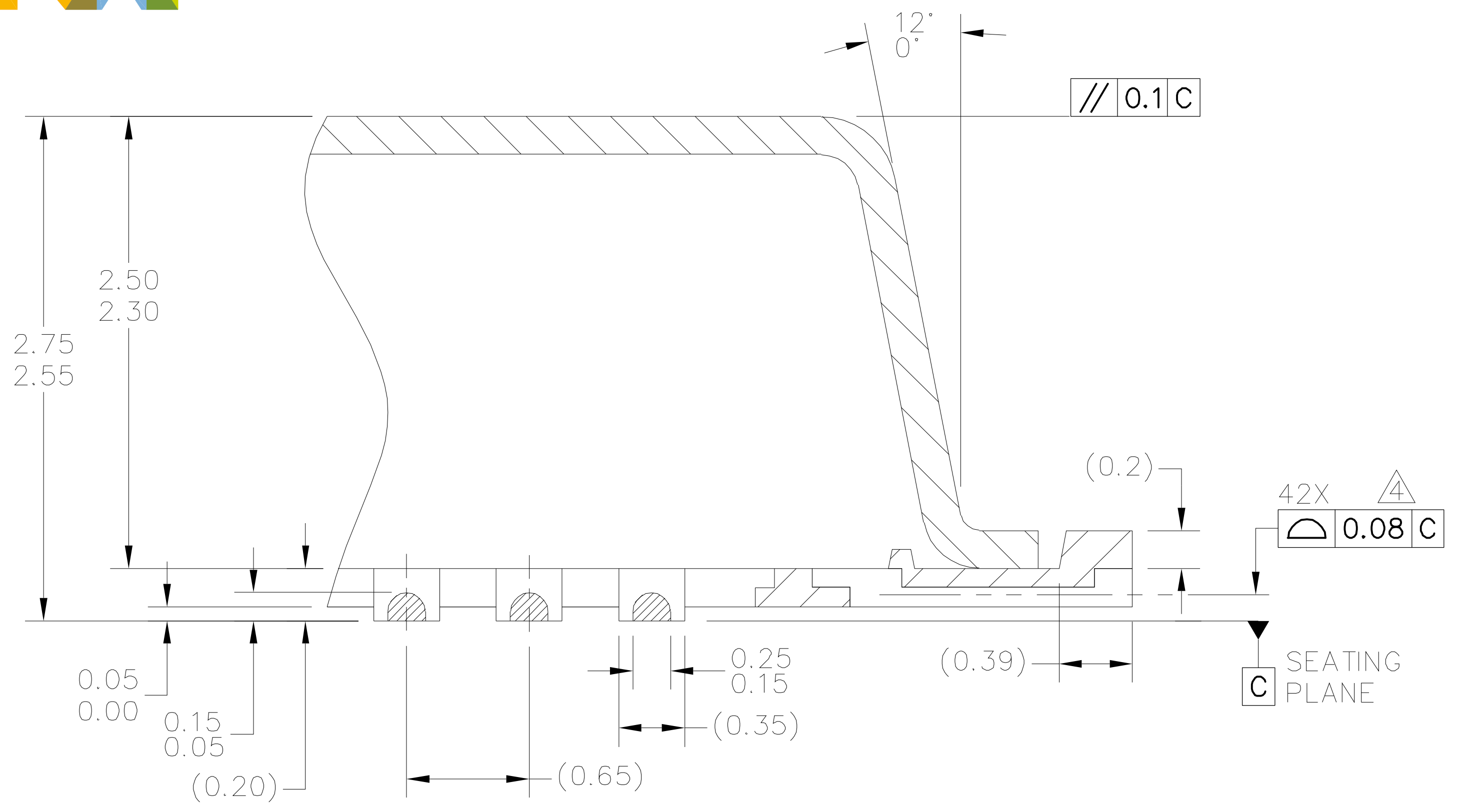
MECHANICAL OUTLINE

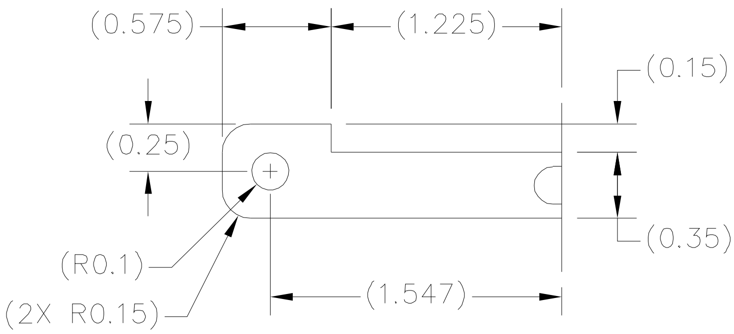
PRINT VERSION NOT TO SCALE

TITLE: SENSOR QFN, THERMALLY ENHANCED, 13.6 X 9 X 2.65, 0.65 PITCH, 42 TERMINAL	DOCUMENT NO: 98ASA00427D	REV: B
	STANDARD: NON-JEDEC	
	SOT1682-1	08 JAN 2016





DETAIL G
VIEW ROTATED 90° CW



DETAIL H

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. THIS IS NON JEDEC REGISTERED PACKAGE.

4. (△) COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH FLAG.

5. MIN METAL GAP BETWEEN TERMINAL AND DIE PADDLE SHALL BE 0.25MM.

6. (△) THIS DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM TERMINAL TIP.

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